Abstracts

Surface mount microwave package characterization technique

A. Pham, C. Chun, J. Laskar and B. Hutchison. "Surface mount microwave package characterization technique." 1997 MTT-S International Microwave Symposium Digest 2. (1997 Vol. II [MWSYM]): 995-998.

We present a plastic package characterization technique using coplanar waveguide to package adapters (CPA) and line-reflect-match (LRM) calibrations. LRM calibrations on off-set CPA standards are employed to de-embed the response of CPA adapters in measured S-parameters. A variety of small shrink outline packages (SSOP) has been characterized to 26.5 GHz using this technique.

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